|  |  |  |
| --- | --- | --- |
| C:\Users\ba\AppData\Local\Microsoft\Windows\Temporary Internet Files\Content.IE5\R9YC35I5\LG-0001-OHB_02_Logo OHB AG.jpg | **MIP REPORT** | Date: 29.03.2016 |
| **SO-CAU-OHB–RP-49** | | |
| **1. INSPECTED UNIT** | | |
| Part number | --- | |
| Part name: | STEP-LVPS | |
| Serial number | AA1 | |
|  |  | |
| **2. INSPECTION TYPE** | | |
| Type of inspection (solder, coating, final …) | solder / gluing | |
|  | **P**ass/ **F**ail/ **C**omments | |
| Connectors/Saver | Pass / NA | |
| Hardware assembly | Pass | |
| Gluing | Pass | |
| Soldering | Pass | |
| Cleanliness | Pass | |
| **3. RESULTS** | | |
| Part acceptable? | PCB accepted / zur weiteren Verarbeitung freigegeben | |
|  |  | |
| **4. COMMENTS** | | |
| Build due to Manufacturing Flow Chart: **STEP-LVPS-Board-OHB-XI-11**  On Digital-Board, all Flat-IC´s have to be glued (gluing-plan prepared by CAU) on the LVPS-Board, the Flat-IC`s (Flat10 and Flat14) don’t have to be glued (gluing-plan prepared by OHB) | | |
| **5 SIGNATURE** | | |
| Inspection performed: M. Quack 29.03.2016  Name Date Signature | | |

|  |
| --- |
| **G:\DCIM\100NIKON\DSCN8333.JPG** |
| **G:\DCIM\100NIKON\DSCN8334.JPG** |

|  |
| --- |
| **G:\DCIM\100NIKON\DSCN8335.JPG** |
| **G:\DCIM\100NIKON\DSCN8336.JPG** |

|  |
| --- |
| **G:\DCIM\100NIKON\DSCN8337.JPG** |
| **G:\DCIM\100NIKON\DSCN8338.JPG** |